

2.0x1.25mm SMD CHIP LED LAMP

Part Number: APHBM2012SURKCGKC

Hyper Red Green

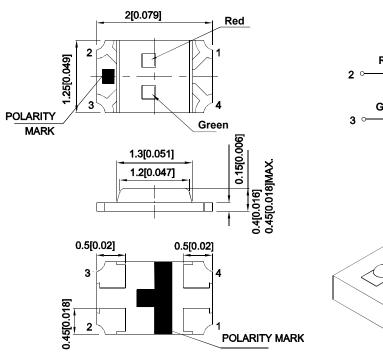
Features

- 2.0mmx1.25mm SMD LED, 0.45mm max. thickness.
- Bi -color, low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

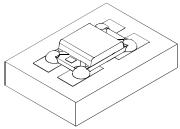
Descriptions

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAG7623 **APPROVED: Wynec**

REV NO: V.12A CHECKED: Allen Liu

DATE: MAY/18/2016 DRAWN: M.Liu

PAGE: 1 OF 6 ERP: 1203005979

Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APHBM2012SURKCGKC	Hyper Red (AlGaInP)	- Water Clear	120	250	- 120°
			*40	*80	
	Green (AlGaInP)		20	50	
			*20	*50	

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	645 574		nm IF=20mA	
λD [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	I==20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	I==20mA
С	Capacitance	Hyper Red Green	35 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	I==20mA
lR	Reverse Current	Hyper Red Green		10 10	uA	V _R = 5V

Notes:

- Wavelength: +/-1nm.
 Forward Voltage: +/-0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

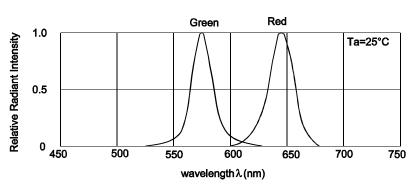
Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Units		
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	185	150	mA		
Reverse Voltage		V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

- Notes:
 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

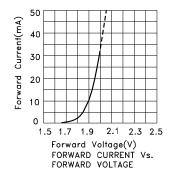
SPEC NO: DSAG7623 **REV NO: V.12A DATE: MAY/18/2016** PAGE: 2 OF 6 ERP: 1203005979 APPROVED: Wynec **CHECKED: Allen Liu** DRAWN: M.Liu

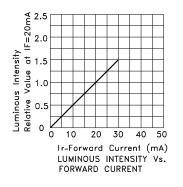
Luminous intensity / luminous Flux: +/-15%.
 Luminous intensity value is traceable to CIE127-2007 standards.

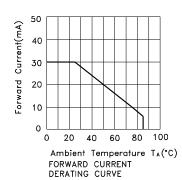


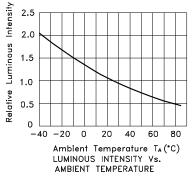
Relative Intensity Vs. Wavelength

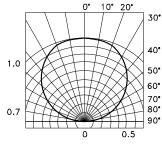
APHBM2012SURKCGKC Hyper Red









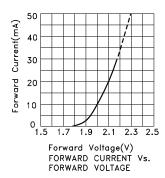


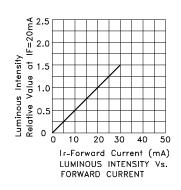
SPATIAL DISTRIBUTION

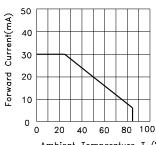
 SPEC NO: DSAG7623
 REV NO: V.12A
 DATE: MAY/18/2016
 PAGE: 3 OF 6

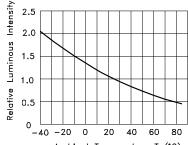
 APPROVED: Wynec
 CHECKED: Allen Liu
 DRAWN: M.Liu
 ERP: 1203005979

Green



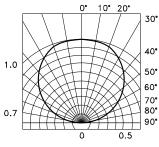












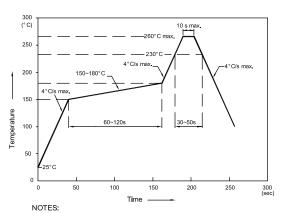
SPATIAL DISTRIBUTION

SPEC NO: DSAG7623 APPROVED: Wynec REV NO: V.12A CHECKED: Allen Liu DATE: MAY/18/2016 DRAWN: M.Liu PAGE: 4 OF 6 ERP: 1203005979

APHBM2012SURKCGKC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

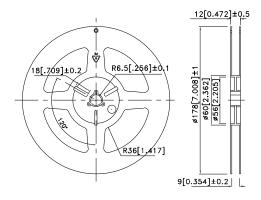


- 1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

9.0

Reel Dimension



Tape Dimensions (Units: mm)

70408
4.0±0.1
4.0±0.1

2.0±0.1

3.2

4.0±0.1

0.53±0.1

0.23±0.1

0.23±0.1

0.23±0.1

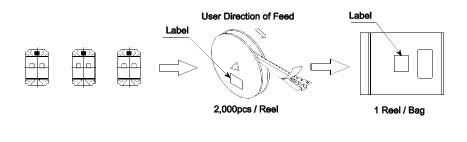
1.4±0.1

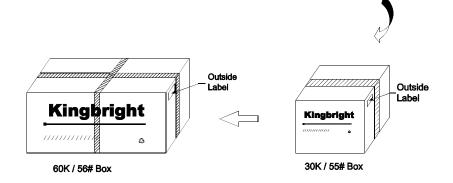
A-A SECTION

SPEC NO: DSAG7623 APPROVED: Wynec REV NO: V.12A CHECKED: Allen Liu DATE: MAY/18/2016 DRAWN: M.Liu PAGE: 5 OF 6 ERP: 1203005979

PACKING & LABEL SPECIFICATIONS

APHBM2012SURKCGKC







Terms and conditions for the usage of this document

- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- $5. \ The \ contents \ and \ information \ of \ this \ document \ may \ not \ be \ reproduced \ or \ re-transmitted \ without \ permission \ by \ Kingbright.$
- $\textbf{6. All design applications should refer to Kingbright application notes available at $\underline{\text{http://www.KingbrightUSA.com/ApplicationNotes}}$$

 SPEC NO: DSAG7623
 REV NO: V.12A
 DATE: MAY/18/2016
 PAGE: 6 OF 6

 APPROVED: Wynec
 CHECKED: Allen Liu
 DRAWN: M.Liu
 ERP: 1203005979